

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	((("6323542") or ("20020008320")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/13 14:52
S2	1963	(257/784).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 13:19
S3	1616	(257/738).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 15:34
S4	2	("0055898").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 15:35
S5	0	("WO55898").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 15:35
S7	0	"repassivation layer" with resin	US-PGPUB; USPAT	OR	ON	2005/05/02 12:33
S8	520	"passivation layer" with resin	US-PGPUB; USPAT	OR	ON	2005/05/02 12:33
S9	141	"passivation layer" near3 resin	US-PGPUB; USPAT	OR	ON	2005/05/02 12:33
S10	78	"passivation layer" near2 resin	US-PGPUB; USPAT	OR	ON	2005/05/02 15:45
S11	50596	resin and irradiation	US-PGPUB; USPAT	OR	ON	2005/05/02 15:46
S12	5355	"resin layer" and irradiation	US-PGPUB; USPAT	OR	ON	2005/05/02 15:47
S13	1014	"resin layer" same irradiation	US-PGPUB; USPAT	OR	ON	2005/05/02 15:47
S14	627	"resin layer" with irradiation	US-PGPUB; USPAT	OR	ON	2005/05/02 15:50
S15	232296	"resin layer" with irradiation and dry etching	US-PGPUB; USPAT	OR	ON	2005/05/02 15:50

S16	70	"resin layer" with irradiation and "dry etching"	US-PGPUB; USPAT	OR	ON	2005/05/02 16:08
S17	2	("6177731").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 16:18
S18	3723	hanaoka.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/02 16:20
S19	0	"hanaoka, teruano".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/02 16:25
S20	0	"hanaoka teruano".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/02 16:19
S21	0	(hanaoka and teruano).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/02 16:19
S22	0	"teruano hanaoka".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/02 16:20
S23	0	S18 and teruano	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/02 16:24
S25	43	"hanaoka, terunao".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/02 16:25
S26	16369	resin and irradiation and (curv\$3 or concave or depress\$3)	US-PGPUB; USPAT	OR	ON	2005/05/03 09:54

S27	6278	resin and irradiation and (concave or depress\$3)	US-PGPUB; USPAT	OR	ON	2005/05/03 09:54
S28	93	resin with irradiation with (concave or depress\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:09
S29	0	"thermosetting resin" and "resin precursor" and etch\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:11
S30	6196	"thermosetting resin" and etch\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:10
S31	82	"thermosetting resin" and "resin precursor" and etch\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:18
S32	3765	etch\$4 and (concave or depress\$3) and irradiation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:23
S33	92	etch\$4 same (concave or depress\$3) same irradiation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:03
S34	7026	etch\$4 same (concaves or hole near2 start\$3 near2 point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:49
S35	4121	etch\$4 with (concaves or hole near1 start\$3 near1 point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:49

S36	2	etch\$4 with (hole near1 start\$3 near1 point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:50
S37	1491	etch\$3 near3 (concaves or hole near1 start\$3 near1 point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:51
S38	916	etch\$3 near2 (concaves or hole near1 start\$3 near1 point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:51
S39	284	etch\$3 adj (concaves or hole near1 start\$3 near1 point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:53
S40	325	etch\$3 with (start\$3 near1 point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 10:53
S41	96	etch\$3 near2 (start\$3 near1 point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 11:00
S42	1813	"etch pit"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 11:00
S43	6	"etch pit" with resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 11:01

S44	2	("20020167013").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 11:02
S46	2	("6455408").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/04 10:02
S47	11	"thermosetting resin" and "resin precursor" and irradiation and (dry adj etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:06
S48	12	(thermoset\$4 adj resin) and "resin precursor" and (irradiation or uv) and (dry adj etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:08
S49	11	(thermoset\$4 adj resin) and "resin precursor" and (radiation or uv) and (dry adj etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:09
S50	13	(thermoset\$4 adj resin) and "resin precursor" and (radiation or uv or ultraviolet or ultra-violet) and (dry adj etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:10
S51	571	(thermoset\$4 adj resin) and (radiation or uv or ultraviolet or ultra-violet) and (dry adj etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:11
S52	3	(thermoset\$4 adj resin) with (radiation or uv or ultraviolet or ultra-violet) with (dry adj etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:12

S53	6	(thermoset\$4 adj resin) same (radiation or uv or ultraviolet or ultra-violet) same (dry adj etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:21
S54	3805	(thermoset\$4 adj resin) with (radiation or uv or ultraviolet or ultra-violet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:22
S55	115	"thermosetting resin" with layer with (irradiation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:30
S56	232	((("thermosetting" or "uv curable") near2 resin) with layer with (irradiation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:48
S64	1890	((("thermosetting" or "uv curable") adj resin) adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:11
S67	74	S64 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:58
S69	34	S64 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 10:58
S70	219	((("uv curable") adj resin) adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:14

S71	2	S70 and ("257"/\$.ccls or "438"/\$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:13
S72	24899	resin with (radiation or irradiation or uv or ultraviolet) with layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:15
S73	16959	resin with (uv curable) with layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:15
S74	4508	resin near2 (uv curable) near2 layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:19
S75	2272	resin adj layer near2 (uv curable)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:16
S76	26	S75 and ("257"/\$.ccls. or "438"/\$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:20
S77	627	resin near2 "uv curable" near2 layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:21
S78	256	resin adj layer near2 "uv curable"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:20

S79	268	resin adj layer near3 "uv curable"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:21
S80	5	S79 and ("257"/\$.ccls. or "438"/\$. ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:22
S81	1173	resin adj layer near2 ("uv curable" or irradiation or radiation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 11:22
S82	36	S81 and ("257"/\$.ccls. or "438"/\$. ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 13:43
S83	2	("6455408").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/04 13:43
S85	5093	(resin or epoxy) with (solubility or soluble) with (radiat\$3 ro irradiat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:04
S86	4989	(resin) with (solubility or soluble) with (radiat\$3 ro irradiat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:13
S87	89	(resin) with (solubility or soluble) with (radiat\$3 ro irradiat\$3) with etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/12 15:14

S88	58	"438"/\$.ccls. and ("wiring layer" with (concave or curv\$2))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/13 15:15
S89	6	((("6166444") or ("6767817") or ("20040245621")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/13 15:15